

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| L2 | 63 | (nonfunct\$5 adj (die chip ic)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/02/01 17:41 |
| L3 | 33 | 257/48.ccls. and (die wafer chip ic) with segment | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 17:50 |
| L4 | 79 | (nonfunct\$5 adj (die chip ic)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 17:41 |
| L5 | 92 | 257/723-724.ccls. and (die wafer chip ic) with segment | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 18:01 |
| L6 | 6 | ((("6627917") or ("6486005") or ("6744067"))).PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/02/01 17:55 |
| L7 | 96 | 257/773,737-738.ccls. and (die wafer chip ic) with segment | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 18:28 |
| L8 | 100 | 257/690,778.ccls. and (die wafer chip ic) with segment | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 18:35 |
| L9 | 92 | 257/723-724.ccls. and (die wafer chip ic) with segment | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/02/01 19:33 |
| L11 | 37 | (wafer adj segment) with (chip die) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/02/01 19:35 |